

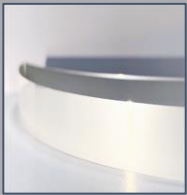
- wire for LN₂

any customization



Parameter	Value	
Substrate thickness	40 μm	
Tensile strength *	> 500 MPa	
Critical deformation*	0.4%	
Critical bend diameter *	< 10 mm	
Wire width, mm	4.0	12.0
Min. critical current @ 77 K, s.f.	100-200 A	400-600 A
Critical current standard deviation	≤ 5%	

* I_c retention ≥ 95%



silver



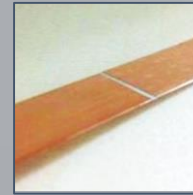
copper



solder



insulation



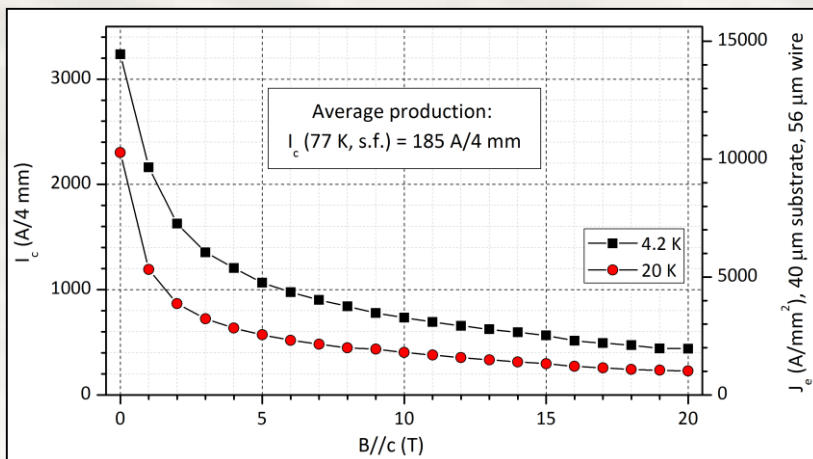
low resistance joints



lamination and stacks

- wire for in-field applications

Average production I _c A/4 mm					
→ B//c	s.f.	5 T	10 T	15 T	20 T
20 K	1800 A	425 A	285 A	220 A	180 A
4.2 K	2600 A	720 A	490 A	380 A	320 A



1000 A/mm² @ 20 K, 20 T
 2000 A/mm² @ 4.2 K, 20 T

2020 world record!
 commercially available
 product